NCE N-Channel Super Trench Power MOSFET

Description

The NCEP02T10D uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS}(\text{ON})}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

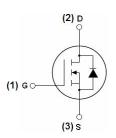
- V_{DS} =200V, I_{D} =100A $R_{DS(ON)}$ <12mΩ @ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product
- Very low on-resistance R_{DS(on)}
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

100% UIS TESTED!

100% ΔVds TESTED!



Schematic diagram



Marking and pin assignment



TO-263-2L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP02T10D	NCEP02T10D	TO-263-2L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	200	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	100	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	70.7	Α
Pulsed Drain Current	I _{DM}	400	Α
Maximum Power Dissipation	P _D	300	W
Derating factor		2	W/℃
Single pulse avalanche energy (Note 1)	E _{AS}	1216	mJ
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 175	$^{\circ}$

NCEP02T10D

Thermal Characteristic

Thermal Resistance, Junction-to-Case Rejc 0.5 *C/W
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Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			<u> </u>			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	200	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =200V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	2.5		4.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =50A	-	10	12	mΩ
Forward Transconductance	g FS	V _{DS} =10V,I _D =50A	70	-	-	S
Dynamic Characteristics						
Input Capacitance	C _{lss}		-	6000	-	PF
Output Capacitance	Coss	V_{DS} =100V, V_{GS} =0V, F=1.0MHz	-	425	-	PF
Reverse Transfer Capacitance	Crss	F=1.UMHZ	-	16	-	PF
Switching Characteristics (Note 2)	·					
Turn-on Delay Time	t _{d(on)}		-	18	-	nS
Turn-on Rise Time	t _r	V_{DD} =100 V , I_D =50 A	-	26	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =4.7 Ω	-	41	-	nS
Turn-Off Fall Time	t _f		-	11	-	nS
Total Gate Charge	Qg	\/ 400\/ 504	-	87		nC
Gate-Source Charge	Q _{gs}	V _{DS} =100V,I _D =50A,	-	32		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	17.5		nC
Drain-Source Diode Characteristics			<u> </u>			
Diode Forward Voltage	V _{SD}	V _{GS} =0V,I _S =100A	-		1.2	V
Diode Forward Current	Is		-	-	100	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 50A	-	140		nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs	-	600		nC

Notes:

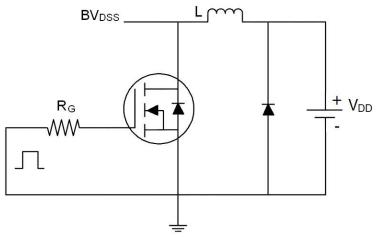
^{1.} EAS condition : Tj=25 $^{\circ}\mathrm{C}$,V_DD=50V,V_G=10V,L=0.5mH,Rg=25 Ω

^{2.} Guaranteed by design, not subject to production

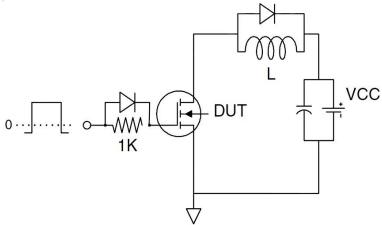
^{3.} These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsin k, assuming a maximum junction temperature of $TJ(MAX)=175^{\circ}$ C. The SOA curve provides a single pulse rating.

Test Circuit

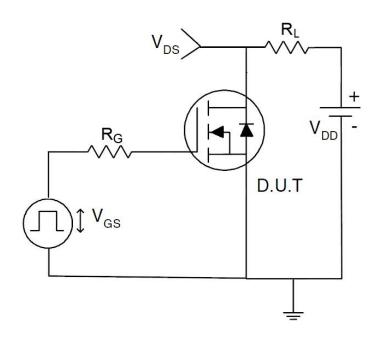
1) E_{AS} test Circuit

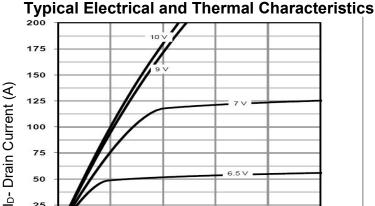


2) Gate charge test Circuit



3) Switch Time Test Circuit





Vds Drain-Source Voltage (V) **Figure 1 Output Characteristics**

25

0

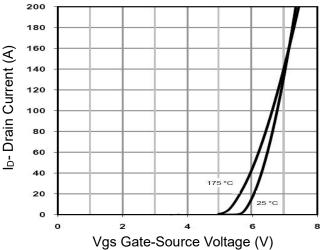


Figure 2 Transfer Characteristics

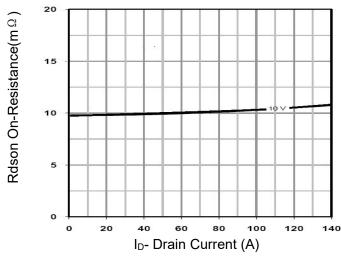


Figure 3 Rdson- Drain Current

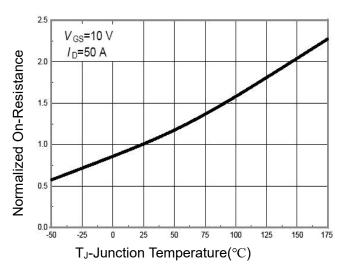


Figure 4 Rdson-JunctionTemperature

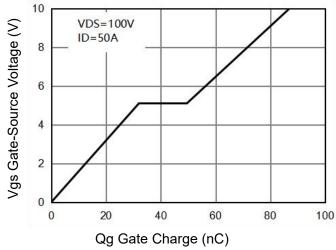


Figure 5 Gate Charge

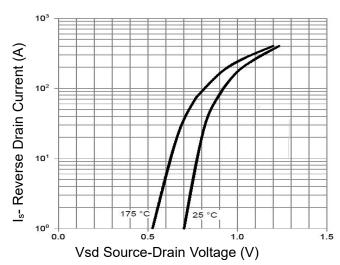


Figure 6 Source- Drain Diode Forward

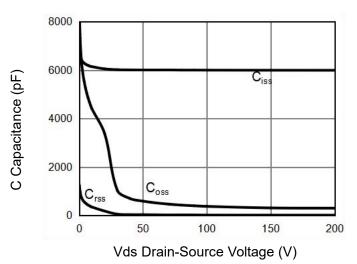


Figure 7 Capacitance vs Vds

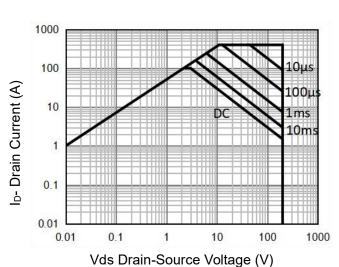


Figure 8 Safe Operation Area(Note 3)

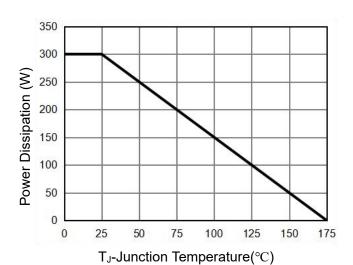


Figure 9 Power De-rating

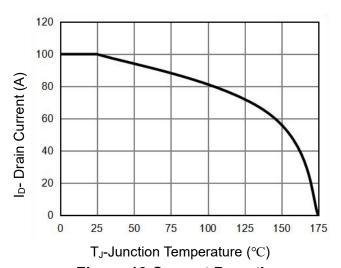


Figure 10 Current De-rating

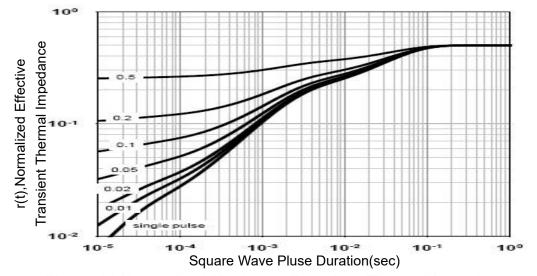
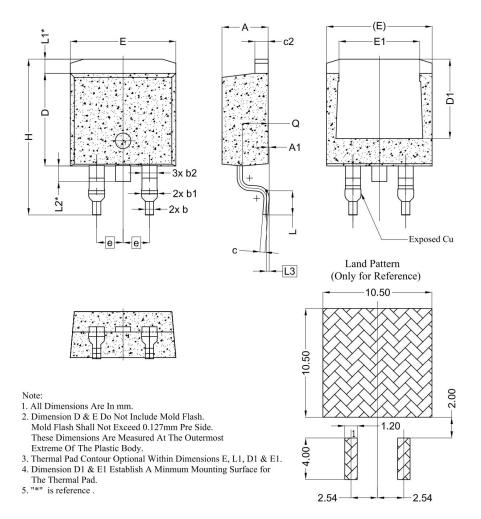


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-263-2L Package Information



SYMBOL	DIMENSIONS			
STIVIBUL	MIN.	NOM.	MAX.	
Α	4.24	4.44	4.64	
A1	0.00	0.10	0.25	
b	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1.20	1.45	1.70	
С	0.40	0.50	0.60	
c2	1.15	1.27	1.40	
D	8.82	8.92	9.02	
D1	6.86	7.65	_	
Е	9.96	10.16	10.36	
E1	6.89	7.77	7.89	
е				
Н	14.61	15.00	15.88	
L	1.78 2.32		2.79	
L1	1.36 REF.			
L2	L2 1.50 REF.			
L3	L3 0.25 BSC Q 2.30 2.48 2.70			
Q				

NCEP02T10D

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